

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"6717267".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 14:23
L2	2	"6,600,175".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 16:15
L3	0	2 and power with 25b	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 16:16
L4	0	2 and power same 25b	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 16:16
L5	0	2 and 25b	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 16:16
L6	0	1 and power with 25b	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 16:16
L7	1	1 and power same 25b	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 16:41
L8	2	"5177594".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 17:29
L9	1346	siN with metallic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 17:29

L10	124	siN near2 metallic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 18:17
L11	3167	substrate with pin with board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 18:18
L12	229	substrate with pin with direct\$4 with board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 18:18
L13	62	12 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 18:18
L14	9	("20020011662" "20020074653" "20020185308" "5939782" "6353540" "6400576" "6518666" "6535398" "6727780").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 18:19
L15	20	("4322778" "4574255" "4755910" "4811082" "4901136" "5014114" "5032896" "5075253" "5077639" "5095402" "5177670" "5237204" "5239198" "5239448" "5255431" "5384691" "5473513" "6018463" "6147876" "6153290").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 18:21
L16	111	("4064552" "4081898" "4104728" "4177519" "4495546" "4567543" "4598337" "4672152" "4744008" "4754371" "4843520" "4926241" "4933810" "4937707" "4967950" "4982376" "4987100" "4990948" "5028983").PN. OR ("5239448"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 18:24
L17	11	("4612083" "4939568" "5138437" "5191405" "5202754" "5239448" "5266511" "5380681" "5489554" "5579207").PN. OR ("6593645"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 18:27
L18	2419	(257/773).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/12 21:03

L19	43	L18 and heat with interconnect\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L20	105	("3539705" "3846166" "4096623" "4164461" "4308090" "4601915" "4670091" "4849070").PN. OR ("5117276").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L21	11	("5117276" "5444015" "5798559" "6245658" "6255712" "6277728" "6386939" "6403461" "6614092").PN. OR ("6713835"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L22	1392	L18 and line	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L23	361	L18 and line with (power signal)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L24	9	("5814844" "5874754" "6091088" "6114767" "6133079" "6177709" "6288447" "6320234" "6326651").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L25	10	dummy near interconnection with heat	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L26	6	("5441915" "5729047" "5811352").PN. OR ("6717267"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L27	10	dummy near interconnection same heat	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L28	11	dummy near interconnection same heat	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/12/12 21:03
L29	1	L28 not L27	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/12/12 21:03
L30	41	dummy near interconnection and heat	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/12/12 21:03

L31	5	(US-20020058411-\$).did. or (US-6800883-\$ or US-6717267-\$ or US-6913990-\$ or US-6664642-\$). did.	US-PGPUB; USPAT	OR	ON	2005/12/12 21:03
L32	51	interconnection with heat adj transfer and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L33	641	(via damascene) with heat adj transfer and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L34	9	(damascene) with heat adj transfer and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L35	4	(via near4 dummy) with heat adj transfer and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L36	0	(interconnect near4 dummy) with heat adj transfer and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L37	0	(interconnect near4 dummy) with heat adj transf\$3 and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L38	0	(interconect near4 dummy) with heat adj transf\$3 and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L39	0	(interconnecting near4 dummy) with heat adj transf\$3 and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03

L40	0	(pattern near4 dummy) with heat adj transf\$3 and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L41	0	(pattern near4 dummy) with heat adj transf\$4 and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L42	10	(pattern near4 dummy) with heat near2 (transfer\$3 dissipat\$3)and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L43	10	(dummy near4 pattern) with heat near2 (transfer\$3 dissipat\$3)and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L44	1	(dummy near interconnect\$3) with heat near2 (transfer\$3 dissipat\$3)and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L45	3	(dummy near interconnect\$3) with heat near2 (transfer\$3 dissipat\$3)and (IC integrated adj circuit chip die wafer semiconductor silicon).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L46	409	epoxy with phenolic with curing adj accelerator with inorganic adj filler	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L47	78652	heat with dissipation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L48	4261380	(semiconductor ic integrated adj circuit die chip wafer silicon)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03

L49	172616	power near2 line	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L50	220	interconnect with L47	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L51	192	L50 and L48	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L52	16	L51 and L49	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L53	5709	heat with interconnect	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L54	2743	L53 and L48	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L55	152	L54 and L49	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L56	214050	heat with (wir\$3 via damascene trench)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L57	72463	L56 and L48	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03

L58	4279	L56 with L47	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L59	2485	L58 and L48	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L60	102	L59 and L49	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L61	33	L60 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L62	55178	(257/7\$2).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/12 21:03
L63	8561	(257/69\$1).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/12 21:03
L64	59536	L62 L63	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L65	10382	L64 and heat with (dissipat\$3 remov\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L66	8983	L64 and heat near2 (dissipat\$3 remov\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03

L67	5410917	L66 and heat (interconnection via plug wir\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L68	415541	heat with (dissipat\$3 remov\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L69	5408490	(interconnection via plug wir\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L70	24902	L68 with L69	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L71	1755	L64 and L70	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L72	235288	heat near2 (dissipat\$3 remov\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L73	14025	L72 with L69	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L74	1405	L73 and L62	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L75	900	L73 and L62	USPAT	OR	ON	2005/12/12 21:03
L76	2399	(257/774).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/12 21:03

L77	46	L73 and L76	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L78	3534	(257/758).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/12 21:03
L79	32	L73 and L78	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L80	4	("5698897" "5792677").PN. OR ("6242807").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L81	826	(257/760).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/12 21:03
L82	4	L73 and L81	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L83	360	(257/761).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/12 21:03
L84	4	L73 and L82	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03
L85	5084	(257/76\$1).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/12 21:03
L86	18	L73 and L85	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:03

L87	9	("5700735" "5736791" "5739587" "5891799" "5923088" "6028367" "6143396" "6180511" "6251781").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L88	6	("6028367").URPN.	USPAT	OR	ON	2005/12/12 21:03
L89	12	("5248903" "5404047" "5736791" "5739587" "5923088" "5959356").PN. OR ("6028367").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L90	12	("5248903" "5404047" "5736791" "5739587" "5923088" "5959356").PN. OR ("6028367").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L91	3	("5354717" "6018193" "20020061614").pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L92	2	L91 and heat	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L93	1	"6717267".pn. and power	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L94	478	double with heat with sink	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L95	195	L94 and "257"\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:03
L96	145	L94 and "257"\$.ccls.	USPAT	OR	ON	2005/12/12 21:03
L97	57	L96 and wire	USPAT	OR	ON	2005/12/12 21:03
L98	143	andujar.xa.	USPAT	OR	ON	2005/12/12 21:03
L99	0	aluminum near2 thermal with expasion with epoxy	USPAT	OR	ON	2005/12/12 21:03
L100	0	aluminum near2 thermal with expasion	USPAT	OR	ON	2005/12/12 21:03
L101	4624	aluminum near2 thermal	USPAT	OR	ON	2005/12/12 21:03
L102	211	(wir\$2 with interconnection) with copper	USPAT	OR	ON	2005/12/12 21:03